What is claimed is:

1. A method of forming an orientation film on a substrate comprising: providing the substrate on a stage;

positioning a slit coater having a slit nozzle on the substrate; and

spraying an orientaion material on the substrate through the slit nozzle of the slit coater.

2. The method of claim 1, wherein a thickness of the orientation film is about 0.8 \(\mu \) to about 1.0 \(\mu \).

3. The method of claim 1, wherein the one coater sprays an orientation material out of the slit nozzle to has a surface tension.

4. The method of claim 1, wherein the slit nozzle is at a predetermined distance from the substrate.

The method of claim 1, further comprising, providing at least one laser device irradiating a laser beam.

5. The method of claim 5, further comprising, patterning predetermined portions of the orientation film using the laser beam.

6. The method of claim 6, wherein the predetermined portions includes a spraying surface of the orientaion material.

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7. The method of claim 5, wherein the laser includes an eximer laser.

A. A method of forming an orientation film on a substrate comprising: providing the substrate on a stage;
positioning a slit coater having a slit nozzle on the substrate;

spraying an orientaion material on the substrate through the slit nozzle of the slit coater; and

patterning an orientation pattern a predetermined portion of the orientation material.

- 10. The method of claim 9, wherein the patterning the orientation pattern includes irradiating a laser beam.
 - 11. The method of claim 10, wherein the laser includes an eximer laser.
- 12. The method of claim 9, wherein the predetermined portion includes a spraying surface of the orientation material.
 - 13. The method of claim 9, further comprising rubbing the orientation material.
- 14. The method of claim 13, wherein the step of rubbing is performed after the step of spraying.

- 15. The method of claim 13, wherein the step of rubbing is performed after the step of rubbing.
 - 16. A method of forming an orientation film on a substrate, comprising: providing the substrate on a stage;

positioning a slit coater having a slit nozzle and an orientation material, the slit nozzle being at a predetermined distance from the substrate; and

spraying the orientation material on the substrate through the slit nozzle of the slit coater.

- 17. The method of claim 16, wherein a thickness of the orientation film is about 0.8 \mu to about 1.0 \mu .
- 18. The method of claim 16, wherein the slit coater sprays an orientation material out of the slit nozzle to has a surface tension.
 - 19. The method of claim 16, further comprising:
 providing at least one laser device irradiating a laser beam; and
 patterning predetermined portions of the orientation film using the laser beam.
 - 20. The method of claim 19, wherein the laser beam is an eximer laser.

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